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U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Han-Ping PU  
Yu-Po WANG  
Caesar LIN

05/11/01

## 2. Name and address of receiving party(ies):

Name: Siliconware Precision Industries Co., Ltd.Address: No. 123, Sec. 3, Da Fong Road, Tantz

J1046 U.S. PTO  
09/854303  
05/11/01

City: Taihung State/Prov.: \_\_\_\_\_Country: Taiwan, R.O.C. ZIP: \_\_\_\_\_

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

## 3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other \_\_\_\_\_Execution Date: March 21, 2001

Additional name(s) &amp; address(es)

☐ Yes ☒ No

## 4. Application number(s) or registration numbers(s):

09/854303

If this document is being filed together with a new application, the execution date of the application is: May 11, 2001

Patent Application No.

Filing date

05/19/2001 FFRNREIA 00000005 09854303

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B. Patent No.(s)

Additional numbers

☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Peter F. CorlessRegistration No. 33,860Address: EDWARDS & ANGELL, LLP

P.O. Box 9169

City: Boston State/Prov.: MACountry: USA ZIP: 02209

## 6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

## 8. Deposit account number:

04-1105

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless (Reg. No. 33,860)

Name of Person Signing

Signature

May 11, 2001

Date

2

Total number of pages including cover sheet, attachments, and

PATENT

REEL: 011813 FRAME: 0514

1460

# ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

(1) Han-Ping PU (2) Yu-Po WANG (3) Caesar LIN

Inventor(s)  
Full Name(s)

.....  
.....  
.....

hereby sell, assign and transfer to

SILICONWARE PRECISION INDUSTRIES CO., LTD.

Assignee  
Name and  
Address

No. 123, Sec. 3, Da Fong Rd., Tantz, Taichung, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

"CHIP-ON-CHIP BASED MULTI-CHIP MODULE WITH MOLDED UNDERFILL AND METHOD OF

Title of  
Invention

FABRICATING THE SAME"

which application was

Complete  
either  
a) or b)

a) executed by the undersigned on the ..... day of ....., 19 .....  
b) filed on the ..... day of ....., 19 .....

Serial No .....  
including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date

Signed at Tantz, Taichung

this 21st day of March, 2001

Inventor(s)  
Full  
Signature(s)

INVENTOR(S):

Han Ping Pu  
Yu Po Wang  
Caesar Lin

Witnesses'  
Full  
Signatures

WITNESSES: